

IN THE CLAIMS:

Please amend the claims as follows:

1. (currently amended) An electronic device cooling ~~system~~ apparatus, comprising:  
a heat exchange unit configured to deliver cooled air through a cool air conduit to a plurality of cooling interfaces in said cool air conduit; and  
said plurality of at least one cooling interfaces each disposed at a heat-transfer interface of an electronic device and delivering said cooled air to said heat-transfer interface of said electronic device , ~~said cooling interface being thermally coupled to said heat exchange unit; and~~  
~~a heat exhaust thermally coupled to said heat exchange unit, said heat exhaust exhausting heat from said heat exchange unit to a remote location from said electronic device.~~
2. (original) The apparatus of claim 1, wherein said electronic device further comprises a plurality of heat-transfer interfaces wherein said heat-transfer interfaces include an ambient air inlet and a warm air outlet.
3. (currently amended) The apparatus of claim 2, wherein one of said cooling interfaces is disposed at said ambient air inlet.
4. (currently amended) The apparatus of claim 2, wherein one of said cooling interfaces is disposed at said warm air outlet.
5. (original) The apparatus of claim 2, wherein a first cooling interface is disposed at said ambient air inlet of said electronic device, and a second cooling interface is disposed at said warm air outlet of said electronic device.
6. (currently amended) The apparatus of ~~claim 5~~ claim 1, wherein said heat exchange unit is further configured to deliver a liquid coolant to cooling coils disposed in at

least some of said cooling interfaces ~~said first and second cooling interfaces comprise cooling coils.~~

7. (canceled)

8. (currently amended) The apparatus of ~~claim 5~~ claim 6,  
wherein said electronic device further comprises a plurality of heat-transfer interfaces including an ambient air inlet and a warm air outlet;

wherein a first cooling interface is disposed at said ambient air inlet of said electronic device, and a second cooling interface is disposed at said warm air outlet of said electronic device; and

wherein said first cooling interface comprises a cool air conduit and said second cooling interface comprises cooling coils.

9. (currently amended) The apparatus of ~~claim 5~~ claim 6,  
wherein said electronic device further comprises a plurality of heat-transfer interfaces including an ambient air inlet and a warm air outlet;

wherein a first cooling interface is disposed at said ambient air inlet of said electronic device, and a second cooling interface is disposed at said warm air outlet of said electronic device; and

wherein said first cooling interface comprises cooling coils and said second cooling interfaces comprises a cool air conduit.

10. (original) The apparatus of claim 5, wherein said first and second cooling interfaces are disposed within said electronic device.

11. (canceled)

12. (original) The apparatus of claim 1, further comprising a support structure wherein said electronic device and said cooling device are configured to be commonly supported by said support structure.

13. (original) The apparatus of claim 12, wherein said support structure comprises a server rack.

14. (canceled)

15. (original) The apparatus of claim 1, wherein said electronic device is a server.

16-46. (canceled)

47. (new) An cooling system for electronic devices, comprising:  
a plurality of cooling interfaces; and  
a heat exchange unit configured to deliver cooled air to at least a first cooling interface; and liquid coolant to at least a second cooling interface;  
wherein each of said cooling interfaces is disposed at a heat-transfer interface of an electronic device.

48. (new) The system of claim 47, wherein said electronic device further comprises a plurality of heat-transfer interfaces wherein said heat-transfer interfaces include an ambient air inlet and a warm air outlet.

49. (new) The system of claim 48, wherein one of said cooling interfaces is disposed at said ambient air inlet.

50. (new) The system of claim 48, wherein one of said cooling interfaces is disposed at said warm air outlet.

51. (new) The system of claim 47, wherein said first cooling interface is disposed at an ambient air inlet of said electronic device, and said second cooling interface is disposed at a warm air outlet of said electronic device.

52. (new) The system of claim 47, wherein said second cooling interface is disposed at an ambient air inlet of said electronic device, and said first cooling interface is disposed at a warm air outlet of said electronic device.

53. (new) The system of claim 47, wherein said first and second cooling interfaces are disposed within said electronic device.

54. (new) The system of claim 47, further comprising a support structure wherein said electronic device and said cooling system are configured to be commonly supported by said support structure.

55. (new) The system of claim 54, wherein said support structure comprises a server rack.

56. (new) A method of cooling electronic devices comprising delivering cooled air from a heat exchange unit through a cool air conduit to a plurality of cooling interfaces in said cool air conduit, wherein each of said cooling interfaces is disposed at a heat-transfer interface of an electronic device.

57. (new) The method of claim 56, wherein said electronic device further comprises a plurality of heat-transfer interfaces including an ambient air inlet and a warm air outlet, said method further comprising delivering cooled air to a cooling interface located at each of said inlet and said outlet.

58. (new) The method of claim 56, further comprising delivering a liquid coolant to cooling coils disposed in at least some of said cooling interfaces.

59. (new) The method of claim 58, wherein said electronic device further comprises a plurality of heat-transfer interfaces including an ambient air inlet and a warm air outlet, said method further comprising delivering cooled air to a cooling interface located at said inlet and delivering coolant a cooling interface located at said outlet.

60. (new) The method of claim 58, wherein said electronic device further comprises a plurality of heat-transfer interfaces including an ambient air inlet and a warm air outlet, said method further comprising delivering cooled air to a cooling interface located at said outlet and delivering coolant a cooling interface located at said inlet.

61. (new) A method of cooling electronic devices comprising:  
delivering cooled air to at least a first cooling interface; and  
delivering liquid coolant to at least a second cooling interface;  
wherein each of said cooling interfaces is disposed at a heat-transfer interface of an electronic device.

62. (new) The method of claim 61, wherein said electronic device further comprises a plurality of heat-transfer interfaces including an ambient air inlet and a warm air outlet, said method further comprising delivering cooled air to a cooling interface located at said inlet and delivering coolant a cooling interface located at said outlet.

63. (new) The method of claim 61, wherein said electronic device further comprises a plurality of heat-transfer interfaces including an ambient air inlet and a warm air outlet, said method further comprising delivering cooled air to a cooling interface located at said outlet and delivering coolant a cooling interface located at said inlet.

64. (new) A system for cooling electronic devices comprising:  
means for cooling air; and  
means for delivering cooled air to a plurality of cooling interfaces,  
wherein each of said cooling interfaces is disposed at a heat-transfer interface of an electronic device.

65. (new) A system for cooling electronic devices comprising:  
means for delivering cooled air to at least a first cooling interface; and  
means for delivering liquid coolant to at least a second cooling interface;

wherein each of said cooling interfaces is disposed at a heat-transfer interface of an electronic device.